

WHAT IS CLAIMED IS:

1. A method for transferring a transparent conductive film onto one surface of a sheet base material made of a plastic material, wherein said transparent conductive film as an object to be transferred is preliminarily formed on a substrate side which is superior in heat resistance to the plastic material, said transparent conductive film being sandwiched between a peelable layer which can be peeled off at the time of transfer and a protective film for protecting said transparent conductive film on said substrate side which is superior in heat resistance to the plastic material.
2. A transferring method according to claim 1, wherein said substrate which is superior in heat resistance to the plastic material is a substrate made of any one or a combination of ceramic, glass and metal, said peelable layer being made of polyimide resin.
3. A transferring method according to claim 1, wherein an adhesive layer is formed on said protective film which is formed on said substrate which is superior in heat resistance to the plastic material.
4. A transferring method according to claim 3, wherein spacer means for controlling the thickness of said adhesive layer is disposed on said adhesive layer portion.

卷之三

5. A transferring method according to claim 4, wherein said spacer means is either spacer particles mixed into said adhesive layer or a spacer pattern formed on said protective film.

6. A transferring method according to claim 5, wherein said transparent conductive film is an electrode of a liquid crystal color display unit, a color filter layer for color display is formed on said protective film and said adhesive layer covers said color filter layer.

7. A transferring method according to claim 1, wherein said transparent conductive film is made of a metal oxide, said protective film being made of any one or a combination of organic resin and an inorganic compound.

8. A transferring method according to claim 7, the hardness of said protective film is set to a value equivalent to H or more in pencil hardness based on JIS K5401 test.